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TO: Examiner Nitin Parekh FROM: Norman P. Soloway

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☐ URGENT

☐ FOR REVIEW

☐ PLEASE COMMENT

☐ PLEASE REPLY

NOTES/COMMENTS:

AMENDMENT E UNDER RULE 116

In re Appln. Of: MATSUDA
Serial No.: 09/222,524
Filed: December 28, 1998
For: SEMICONDUCTOR DEVICE
Docket: NEC N98039 CON

Received: 1. Amendment E Under Rule 116 (10 pgs)
2. Marked Claims w/cover sheet (8 pgs)

8-19-02 DC

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. Of: MATSUDA

Serial No. 09/222,524

Filed: December 28, 1998

For: SEMICONDUCTOR DEVICE

Group: 2811

Examiner: NITIN PAREKH

DOCKET: NEC N98039 CON

The Assistant Commissioner of Patents & Trademarks
Washington, D.C. 20231

Dear Sir:

AMENDMENT E UNDER RULE 116

This Amendment is being filed in response to the Final Action mailed May 31, 2002.

Please amend the Application as follows:

IN THE CLAIMS:

Please amend independent claims 21-23, 27-29, 33-35 and 39-41 to read as follows:

21. (Twice Amended) A semiconductor device comprising:

a wiring substrate having a predetermined pattern of wiring formed on one surface;

a semiconductor chip disposed on the other surface of said wiring substrate and having at least one chip electrode set comprising at least two chip electrodes in a common wiring layer, wherein said chip electrodes are arranged from an edge of said semiconductor chip toward its inner side;

said wiring substrate having a number of through-holes;

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